

30V N-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

 $V_{(BR)DSS}=30V$; $R_{DS(ON)}=0.11\Omega$; $I_{D}=3.2A$

DESCRIPTION

This new generation of high density MOSFETs from Zetex utilise a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

SOT23-6

FEATURES

- Low on-resistance
- Fast switching speed
- · Low threshold
- Low gate drive
- SOT23-6 package

APPLICATIONS

- DC DC Converters
- Power Management Functions
- Disconnect switches
- Motor control

ORDERING INFORMATION

DEVICE	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZXM62N03E6TA	7	8mm embossed	3000 units
ZXM62N03E6TC	13	8mm embossed	10000 units

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DEVICE MARKING

• 2N03

ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DSS}	30	V
Gate Source Voltage	V _{GS}	± 20	V
Continuous Drain Current (V_{GS} =10V; T_A =25°C)(b) (V_{GS} =10V; T_A =70°C)(b)	I _D	3.2 2.6	А
Pulsed Drain Current (c)	I _{DM}	18	Α
Continuous Source Current (Body Diode) (b)	Is	2.1	Α
Pulsed Source Current (Body Diode)	I _{SM}	18	Α
Power Dissipation at T _A =25°C (a) Linear Derating Factor	P _D	1.1 8.8	W mW/°C
Power Dissipation at T _A =25°C (b) Linear Derating Factor	P_D	1.7 13.6	W mW/°C

THERMAL RESISTANCE

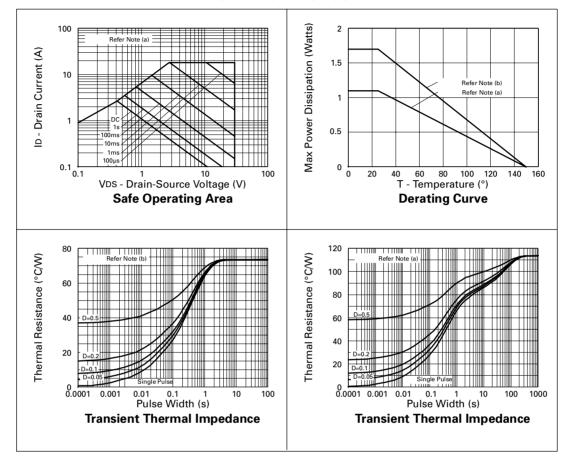
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	113	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	73	°C/W

NOTES

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
- (b) For a device surface mounted on FR4 PCB measured at t≤5 secs.
- (c) Repetitive rating pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.



CHARACTERISTICS





ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.	
STATIC	•			•			
Drain-Source Breakdown Voltage	V _{(BR)DSS}	30			V	I _D =250μA, V _{GS} =0V	
Zero Gate Voltage Drain Current	I _{DSS}			1	μА	V _{DS} =30V, V _{GS} =0V	
Gate-Body Leakage	I _{GSS}			100	nA	V _{GS} =± 20V, V _{DS} =0V	
Gate-Source Threshold Voltage	V _{GS(th)}	1.0			V	$I_D=250\mu A$, $V_{DS}=V_{GS}$	
Static Drain-Source On-State Resistance (1)	R _{DS(on)}			0.11 0.15	Ω	V _{GS} =10V, I _D =2.2A V _{GS} =4.5V, I _D =1.1A	
Forward Transconductance	g _{fs}	1.1			s	V _{DS} =10V,I _D =1.1A	
DYNAMIC (3)	'			<u>'</u>	•		
Input Capacitance	C _{iss}		380		pF	V _{DS} =25 V, V _{GS} =0V, f=1MHz	
Output Capacitance	C _{oss}		90		pF		
Reverse Transfer Capacitance	C _{rss}		30		pF		
SWITCHING(2) (3)			<u> </u>				
Turn-On Delay Time	t _{d(on)}		2.9		ns		
Rise Time	t _r		5.6		ns	$\begin{aligned} &V_{DD} \!=\! 15 \text{V}, &I_{D} \!\!=\! 2.2 \text{A} \\ &R_{G} \!\!=\! 6.0 \Omega, &R_{D} \!\!=\! 6.7 \Omega \\ &\text{(refer to test circuit)} \end{aligned}$	
Turn-Off Delay Time	t _{d(off)}		11.7		ns		
Fall Time	t _f		6.4		ns		
Total Gate Charge	Qg			9.6	nC	V _{DS} =24V,V _{GS} =10V, I _D =2.2A (refer to	
Gate-Source Charge	Q _{gs}			1.7	nC		
Gate Drain Charge	Q_{gd}			2.8	nC	test circuit)	
SOURCE-DRAIN DIODE				-			
Diode Forward Voltage (1)	V _{SD}			0.95	V	T _j =25°C, I _S =2.2A, V _{GS} =0V	
Reverse Recovery Time (3)	t _{rr}		18.8		ns	T _j =25°C, I _F =2.2A,	
Reverse Recovery Charge (3)	Q _{rr}		11.4		nC	di/dt= 100A/μs	
						1	

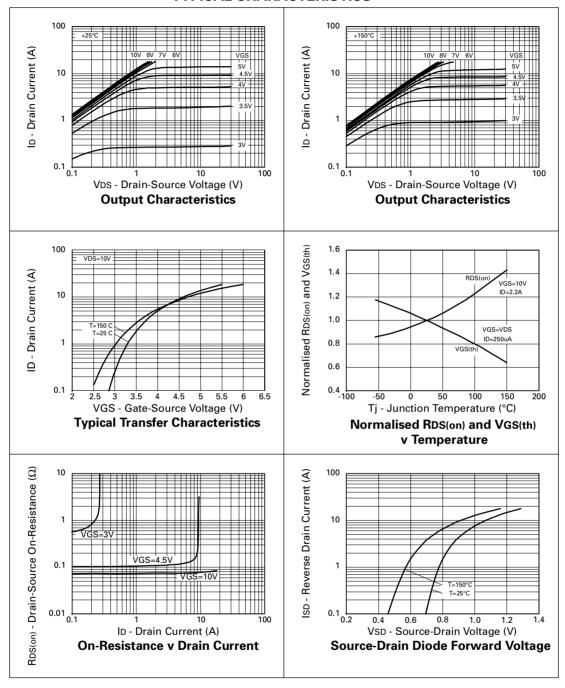
⁽¹⁾ Measured under pulsed conditions. Width=300 μ s. Duty cycle \leq 2% .



⁽²⁾ Switching characteristics are independent of operating junction temperature.

⁽³⁾ For design aid only, not subject to production testing.

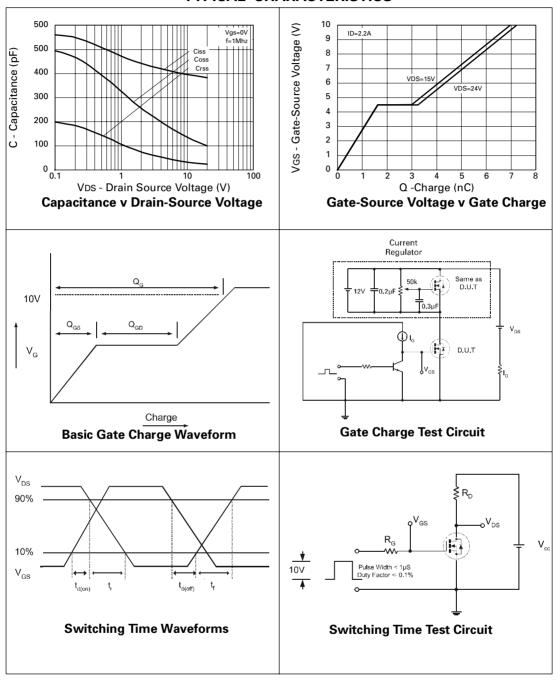
TYPICAL CHARACTERISTICS



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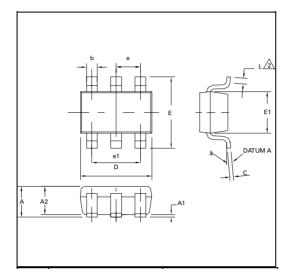
TYPICAL CHARACTERISTICS



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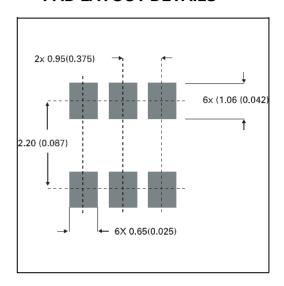


PACKAGE DIMENSIONS



DIM	Millimetres		Inches		
	Min	Max	Min	Max	
Α	0.90	1.45	0.35	0.057	
A1	0.00	0.15	0	0.006	
A2	0.90	1.30	0.035	0.051	
b	0.35	0.50	0.014	0.019	
С	0.09	0.20	0.0035	0.008	
D	2.80	3.00	0.110	0.118	
Е	2.60	3.00	0.102	0.118	
E1	1.50	1.75	0.059	0.069	
L	0.10	0.60	0.004	0.002	

PAD LAYOUT DETAILS





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